



MAS-FIN-153

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By: 

Date: February 18, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applic. No. : 10/090,289 Confirmation No. 6619
Applicant : Johann Winderl
Filed : March 4, 2002
TC/A.U. : 2827
Examiner : Luan C. Thai
Title: : Electronic Component with Stacked
Semiconductor Chips

Docket No. : MAS-FIN-153
Customer No. : 24131

Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

SUPPLEMENTAL AMENDMENT

S i r :

Further to the amendment mailed on January 30, 2004 in response to the Office action dated January 6, 2004, please amend the above-identified application as follows:

Amendments to the Claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks/Arguments begin on page 9 of this paper.